

Memory Subsystem

Contents

- Internal organization of a memory chip
- Organization of a memory unit
- Semiconductor memories: SRAM and DRAM cells.
- Error correction
- Read-Only Memories
- Interleaved Memories
- Cache Memories: Concept, Mapping methods, Caches in commercial processors
- Memory management unit: Concept of virtual memory, Address translation,
- Hardware support for memory management,
- Secondary storage: Hard Disks, RAID, Optical Disks, Magnetic Tape Systems.

Von Neumann Architecture	Harvard Architecture
<ul style="list-style-type: none"> It is ancient computer architecture based on stored program computer concept. 	<ul style="list-style-type: none"> It is modern computer architecture based on Harvard Mark I relay based model.
<ul style="list-style-type: none"> Same physical memory address is used for instructions and data. 	<ul style="list-style-type: none"> Separate physical memory address is used for instructions and data.
<ul style="list-style-type: none"> There is common bus for data and instruction transfer. 	<ul style="list-style-type: none"> Separate buses are used for transferring data and instruction.
<ul style="list-style-type: none"> Two clock cycles are required to execute single instruction. 	<ul style="list-style-type: none"> An instruction is executed in a single cycle.
<ul style="list-style-type: none"> It is cheaper in cost. 	<ul style="list-style-type: none"> It is costly than Von Neumann Architecture.
<ul style="list-style-type: none"> CPU can not access instructions and read/write at the same time. 	<ul style="list-style-type: none"> CPU can access instructions and read/write at the same time.
<ul style="list-style-type: none"> It is used in personal computers and small computers (microprocessors). 	<ul style="list-style-type: none"> It is used in microcontrollers and signal processing.

Basic Concepts: Memory

- **Maximum size** of the memory that can be used in any computer is determined by the addressing scheme.
- **For example:** Suppose, a computer that generates **16-bit** addresses
 - ✓ It is capable of addressing up to $2^{16} = \mathbf{64K}$ (kilo) memory locations.
 - ✓ Similarly, for **32-bit** address computer: $2^{32} = \mathbf{4GB}$ locations
 - ✓ And, for **64-bit** address computer: $2^{64} = \mathbf{16E}$ (exa) $\approx \mathbf{16 \times 10^{18}}$ locations
- The number of locations represents the size of the address space of the computer.

Basic Concepts: Memory

- Digital computer works on stored programmed concept introduced by **Von Neumann**.
- Memory is used to store the **information**, which includes both **program** and **data**.
- Due to several reasons, we have different kind of memories i.e. **at different level different kind of memory** is used.
- **Memory** of computer is broadly categories into two categories:
 - **Internal:** used by CPU to perform task, and
 - **External:** used to store bulk information, including large software and data.

Basic Concepts: Memory Hierarchy

- Programmers want **unlimited amounts** of memory with **low latency**.
- **Fast memory** technology is **more expensive** per bit than slower memory.
- **Solution:** organize memory system into a **hierarchy**.
 - Entire addressable memory space available in largest, slowest memory.
 - Incrementally smaller and faster memories, each containing a subset of the memory below it, proceed in steps up toward the processor.
- The purpose of memory hierarchy is:
 - To **bridge the speed mismatch** between processor and memory at **reasonable cost**.
 - **Minimize the average access time** of entire memory systems

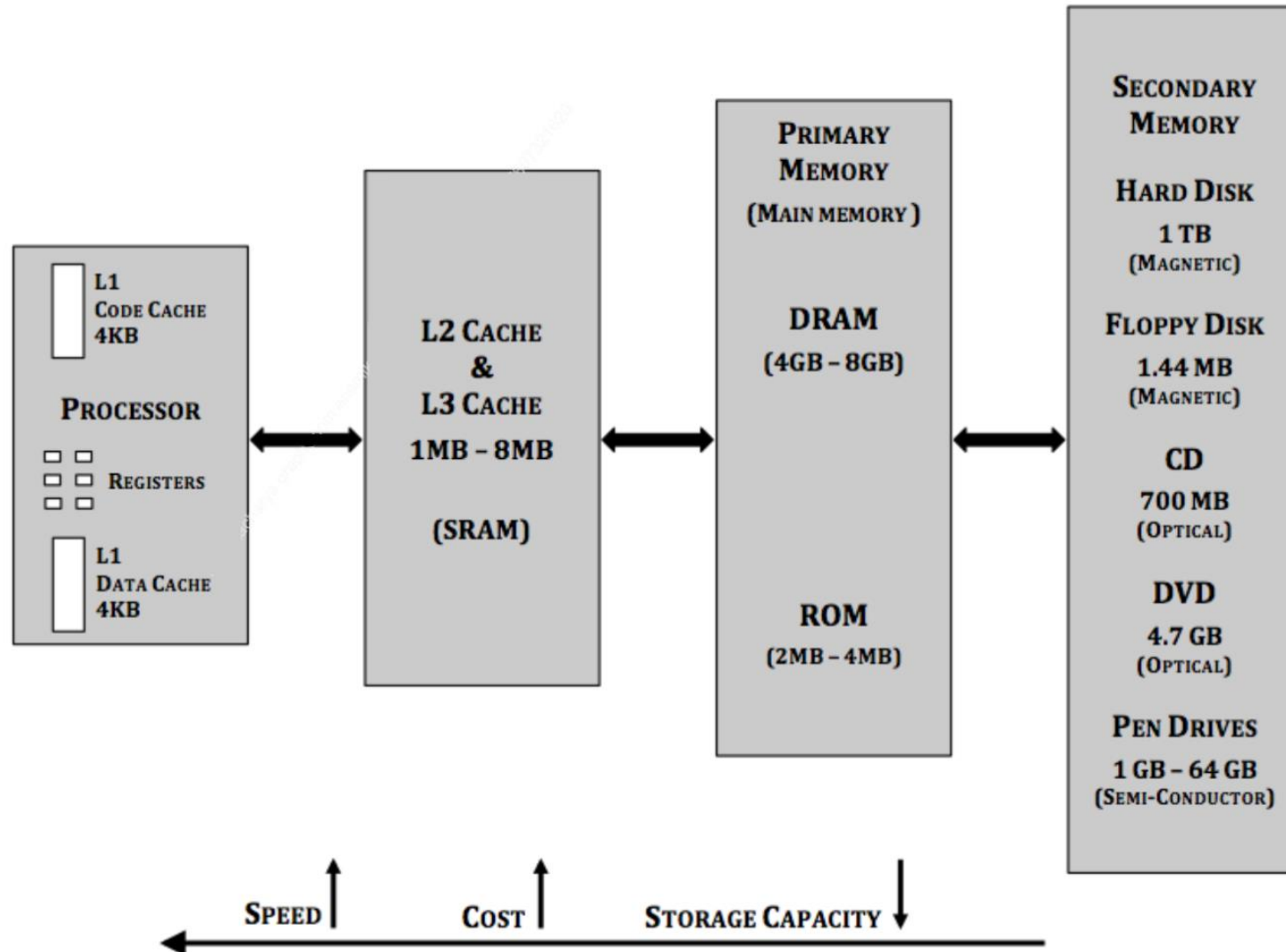
Basic Concepts: Memory Hierarchy

- **Temporal and spatial locality** insures that nearly all references can be found in smaller memories.
 - i.e. Gives the allusion of a large, fast memory being presented to the processor.
- **Locality:**
 - **Spatial Locality:** Data is more likely to be accessed if neighboring data is accessed.

e.g., data in a sequentially access array
 - **Temporal Locality:** Data is more likely to be accessed if it has been recently accessed.

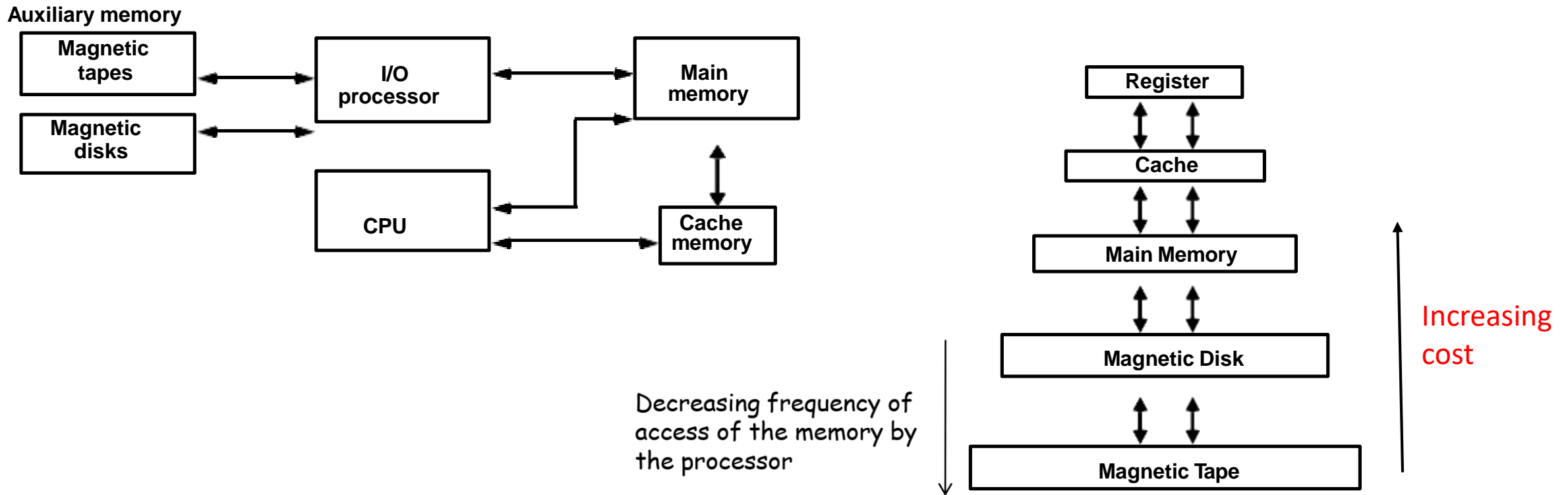
e.g. code within a loop

Basic Concepts: Memory Hierarchy

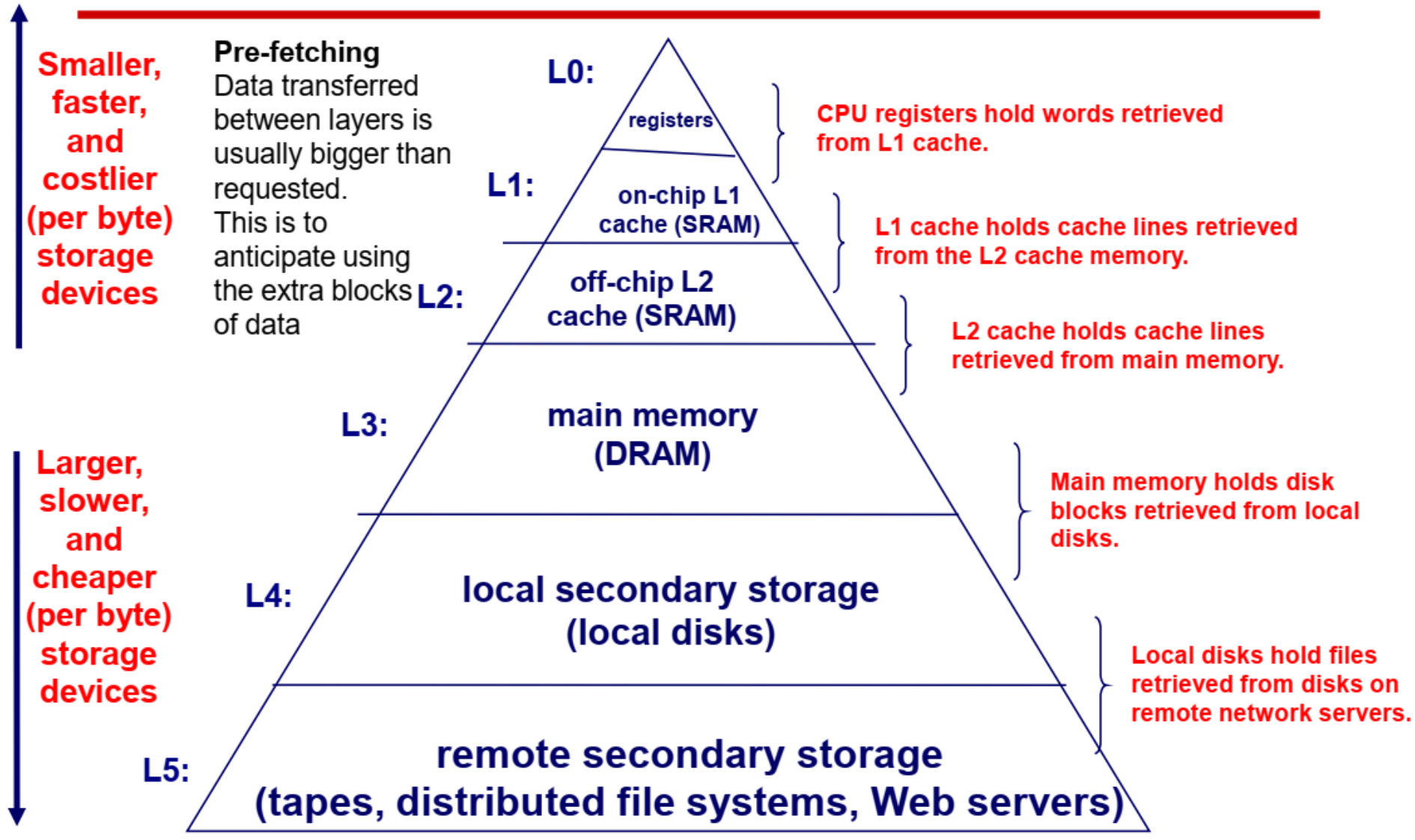


Basic Concepts: Memory Hierarchy

- Memory Hierarchy is to obtain the **highest possible access speed while minimizing the total cost** of the memory system
- Speed of memory access is critical, the idea is to **bring instructions and data** that will be used in the near future **as close to the processor as possible**.

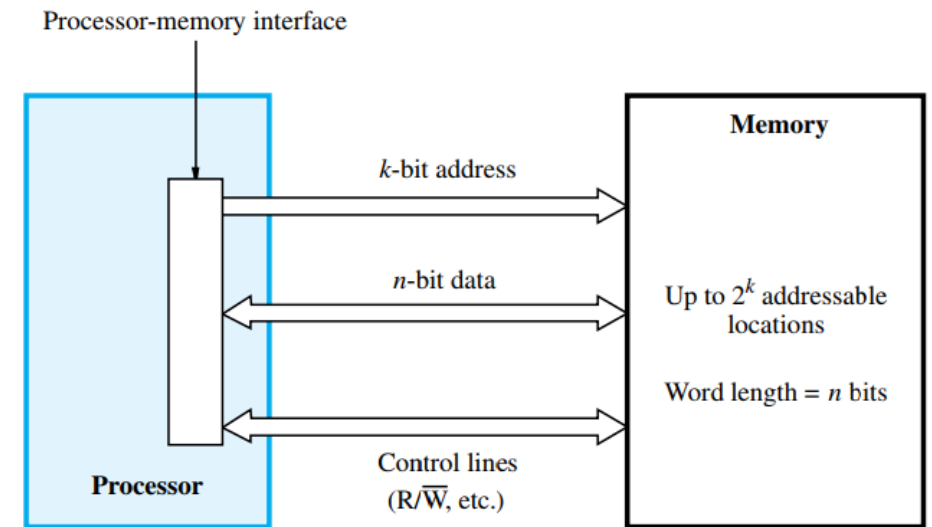


Basic Concepts: Memory Hierarchy Example



Main Memory

- The connection between the processor and its memory consists of **address, data, and control lines**.
- **Address lines** to specify the **memory location** involved in a data transfer operation
 - **Data lines** to transfer the data.
 - At the same time, **control lines** carry the command indicating a Read or a Write operation and whether a byte or a word is to be transferred.
 - **Control lines** also provide the necessary **timing information** and are used by the memory to indicate when it has completed the requested operation.



How to measure Speed of memory units?

- *Memory access time:*

- It is the **time** that elapses between the **initiation of an operation** to transfer a word of data and the **completion of that operation**.
- This is referred to as the *memory access time*.

- *Memory cycle time*

- It is the **minimum time delay** required between **the initiation of two successive memory operations**.
 - For example, the time between two successive Read operations.
- The cycle time is usually slightly longer than the access time, depending on the implementation details of the memory unit.

Random-Access Memory (RAM)

- A memory unit is called a ***Random-access Memory (RAM)*** if the **access time to any location is the same**, independent of the location's address.
- This distinguishes such memory units from **serial, or partly serial**, access storage devices such as **magnetic and optical disks**.
 - Access time of these devices depends on the address or position of the data.
- The technology for implementing computer memories uses **semiconductor integrated circuits**.

Cache Memory

- In general, a processor can process instructions and data faster than they can be fetched from the main memory.
- Hence, the **memory access time is the bottleneck in the system.**
 - **Solution:** use a *cache memory*.
- *Cache memory:*
 - a **small, fast memory** inserted between the larger, slower **main memory** and the **processor**.
 - It holds the currently active portions of a program and their data.

Reading Assignment: **What is Virtual Memory**

Virtual Memory

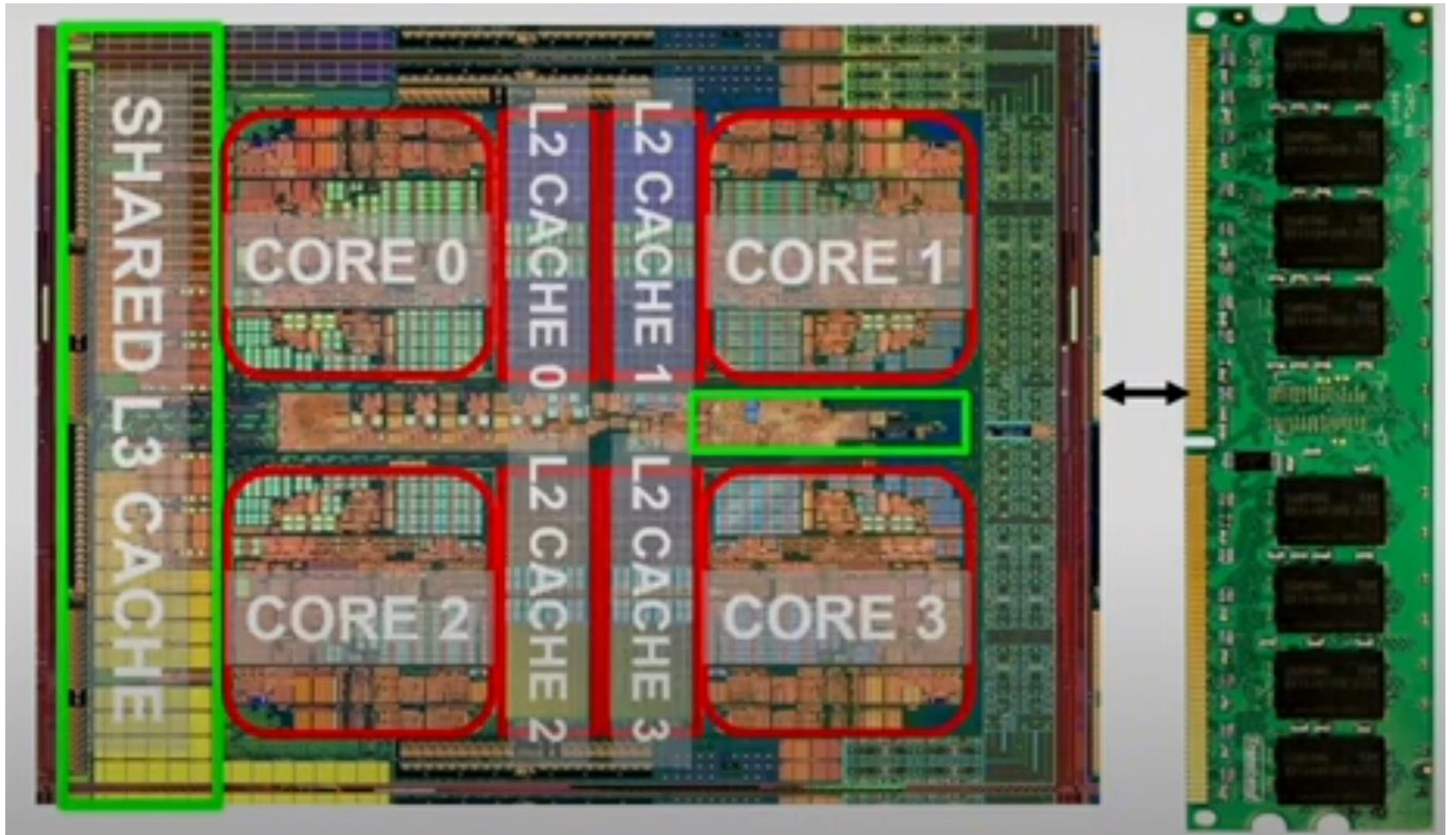
- *Virtual memory* is another important concept related to memory organization.
- **With this technique:**
 - only the **active portions of a program** are stored in the **main memory**, and **remainder** is stored on the much larger **secondary** storage device.
 - Sections of the program are transferred back and forth between the main memory and the secondary storage device in a manner that is transparent to the application program.
 - As a result, the application program sees a memory that is much larger than the computer's physical main memory.

Block Transfers

- As we know, **data move frequently** between the **main memory and the cache** and between the **main memory and the disk**.
- These transfers **do not occur one word at a time**.
- Data are always **transferred in contiguous blocks** involving tens, hundreds, or thousands of words.
 - Data transfers between the main memory and high-speed devices such as a graphic display or an Ethernet interface also involve large blocks of data.
- Hence, a critical parameter for the **performance of the main memory is its ability to read or write blocks of data at high speed**.
- This is an important consideration that we will encounter repeatedly as we discuss memory technology and the organization of the memory system.

Semiconductor RAM Memories

Semiconductor random-access memories (RAMs) are available in a **wide range of speeds**.
Their cycle times range from **100 ns** to less than **10 ns**.

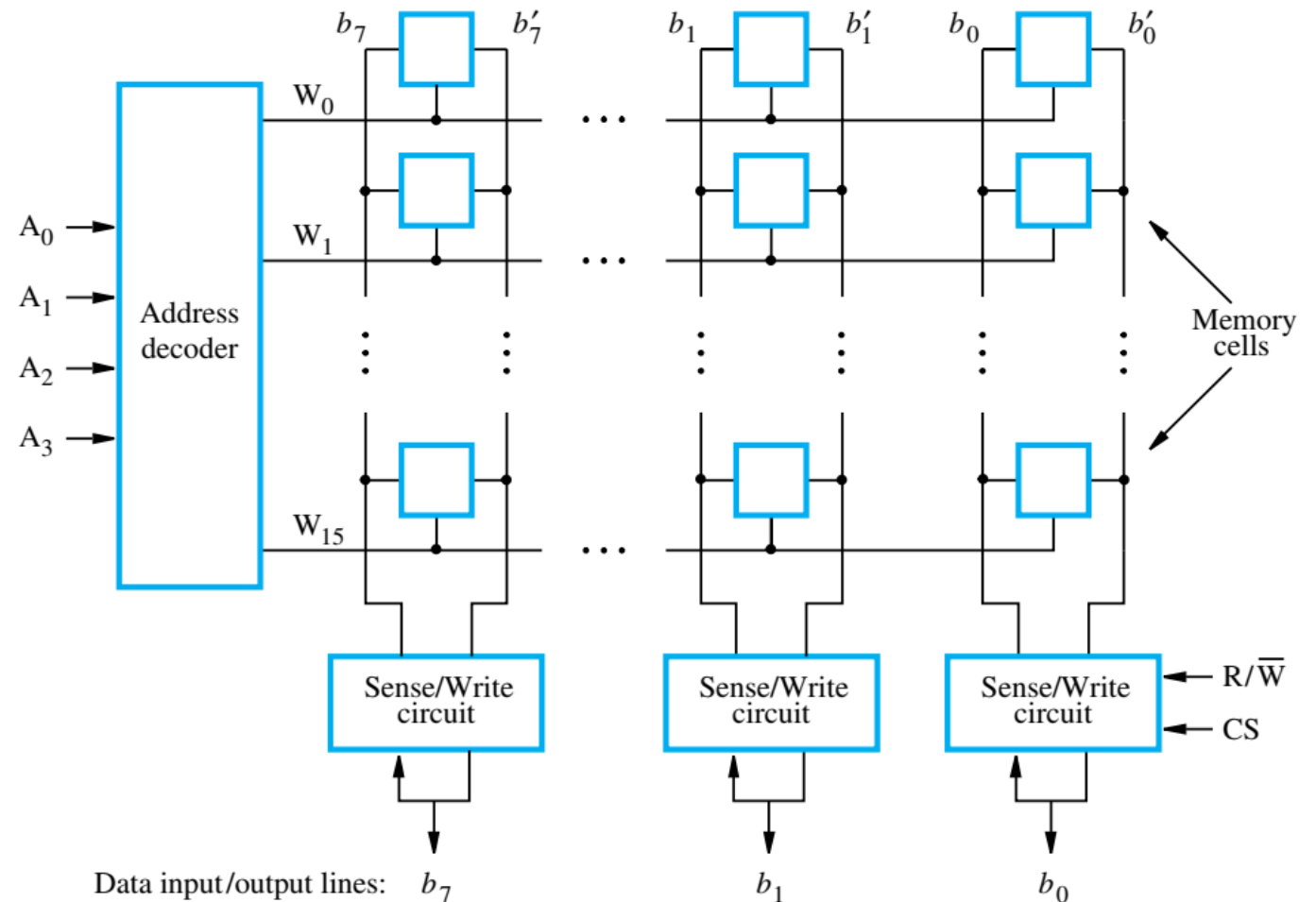


Internal Organization of Memory Chips

- **Memory cells** are usually organized in the form of an **array**, in which **each cell is capable of storing one bit** of information.
- **Each row** of cells constitutes a **memory word** and all **cells of a row** are connected to a common line referred to as the **word line**, which is driven by the address decoder on the chip.
- The **cells in each column** are connected to a **Sense/Write circuit by two bit lines**, and the Sense/Write circuits are connected to the **data input/output lines** of the chip.
- During a **Read operation**, these **circuits sense, or read**, the information stored in the cells selected by a word line and place this information on the output data lines.
- During a **Write operation**, the Sense/Write circuits receive input data and store them in the cells of the selected word.

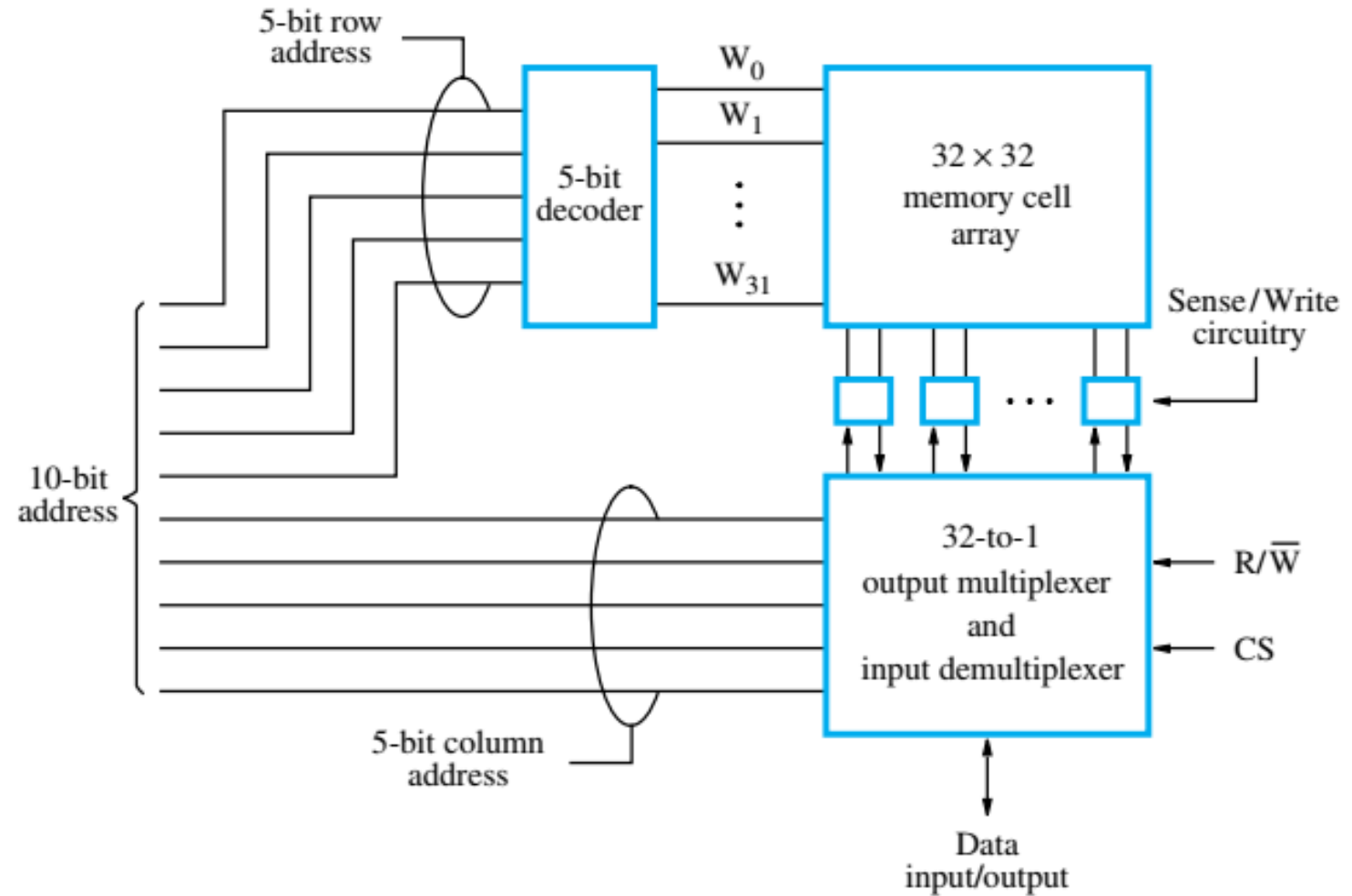
Internal Organization of Memory Chips

- An example of a very small memory circuit consisting of **16 words of 8 bits each**, referred to as a **16×8 organization**.
- Data input and the data output of each Sense/Write circuit are connected to a single bidirectional data line that can be connected to the data lines of a computer.
- Two control lines, R/W and CS, are provided.
- The **R/W (Read/Write)** input specifies the required operation, and the **CS (Chip Select)** input selects a given chip in a multichip memory system.



Internal Organization of Memory Chips

Organization of a
1K × 1 memory chip.



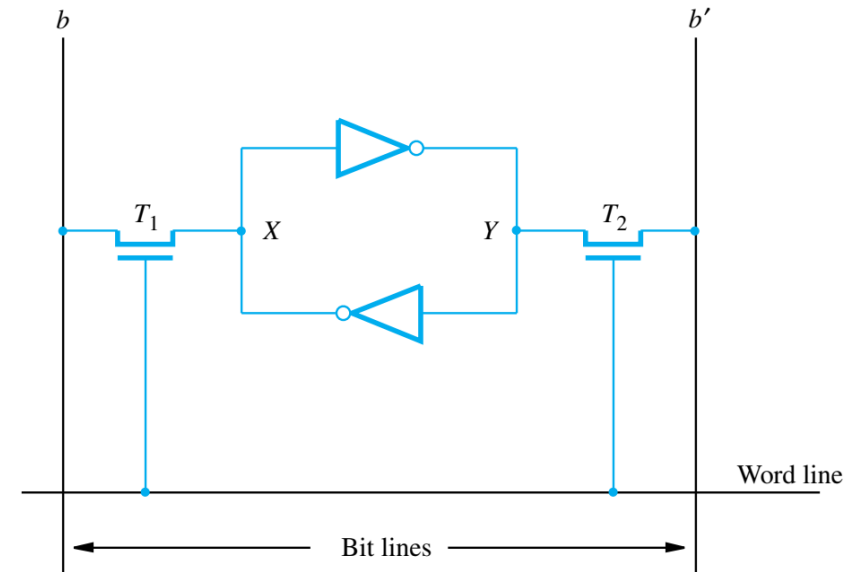
Reading Assignments

- What is CMOS (P-type and N-type transistors)? Working Principle & Its Applications.
- What is field effect transistor (FET)? Working Principle & Its Applications.

Memory Cell: SRAM

Memories that consist of circuits capable of retaining their state as long as power is applied are known as *static memories*.

- Two **inverters** are cross-connected to form a latch and it is connected to two bit lines by transistors T_1 and T_2 .
- These transistors act as switches that can be opened or closed under control of the word line.
- When the word line is at ground level, the transistors are turned off and the latch retains its state.
- **For example,**
 - if the logic value at point X is 1 and at point Y is 0, this state is maintained as long as the signal on the word line is at ground level.
 - Assume that this state represents the **value 1**.



Memory Cell: SRAM

Read Operation:

- In order to **read the state of the SRAM cell**, the word line is activated to close switches T_1 and T_2 .
- If the **cell is in state 1**, the **signal on bit line b is high** and the signal on bit line b' is low.
- The **opposite is true if the cell is in state 0**.
- Thus, b and b' are always complements of each other.
- The Sense/Write circuit at the end of the two bit lines monitors their state and sets the corresponding output accordingly.

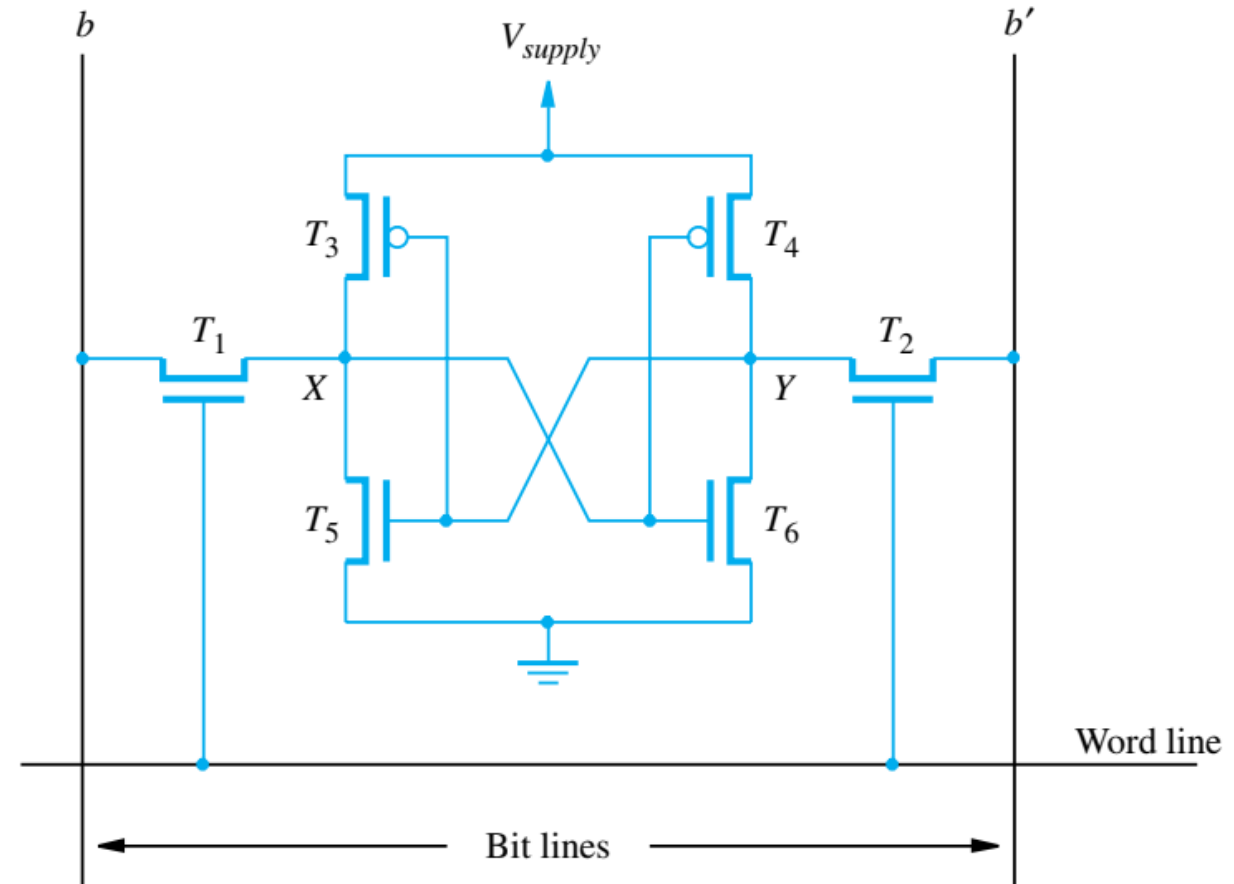
Memory Cell: SRAM

Write Operation:

- During a **Write operation**, the Sense/Write circuit drives **bit lines b and b'** instead of sensing their state.
- It places the appropriate value on **bit line b and its complement on b'** and activates the word line.
- This forces the cell into the corresponding state, which the cell retains when the word line is deactivated.

Memory Cell: SRAM CMOS Cell

- Transistor pairs (T_3 , T_5) and (T_4 , T_6) form the inverters in the latch.
- For example, **in state 1 the voltage at point X is maintained high** by having transistors:
 - T_3 and T_6 **ON**, while T_4 and T_5 are **OFF**.
 - If T_1 and T_2 are turned **ON**, bit lines **b** and **b'** will have high and low signals, respectively.



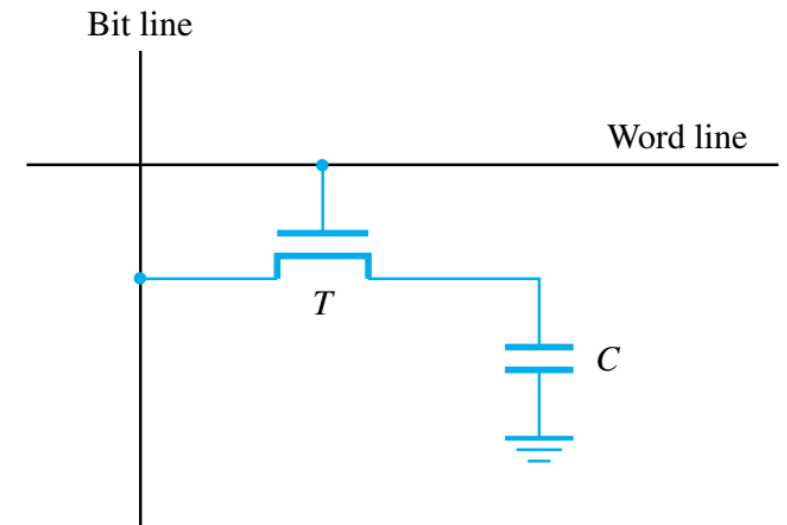
Memory Cell: SRAM CMOS Cell

- **Continuous power is needed for the cell to retain its state.**
- If power is interrupted, the cell's contents are lost.
- When power is restored, the latch settles into a stable state, but not necessarily the same state the cell was in before the interruption.
- Hence, SRAMs are said to be **volatile memories** because their contents are lost when power is interrupted.
- A major **advantage of CMOS SRAMs** is their **very low power consumption**, because current flows in the cell only when the cell is being accessed.
- Otherwise, T_1 , T_2 , and **one transistor in each inverter are turned off**, ensuring that there is no continuous electrical path between V_{supply} and **ground**.
- Static **RAMs can be accessed very quickly**. Access times on the order of a few nanoseconds are found in commercially available chips.
- **SRAMs are used in applications where speed is of critical concern.**

Memory Cell: DRAM

- Static RAMs are fast, but their cells require several transistors → **Expensive**
- **Less expensive** and higher density RAMs can be implemented with simpler cells.
- But, these **simpler cells do not retain their state for a long period**, unless they are accessed frequently for Read or Write operations.
- Memories that use such cells are called *dynamic RAMs (DRAMs)*.

- A DRAM **memory cell** consists of a single **field effect transistor (FET)** and a **capacitor**.
- **Bit stored in a cell in the form of a charge on a capacitor.**
- To store a **bit** in this cell, transistor ***T*** is turned **ON** and an appropriate voltage is applied to the bit line.
- This causes a known amount of charge to be stored in the capacitor.



Memory Cell: DRAM

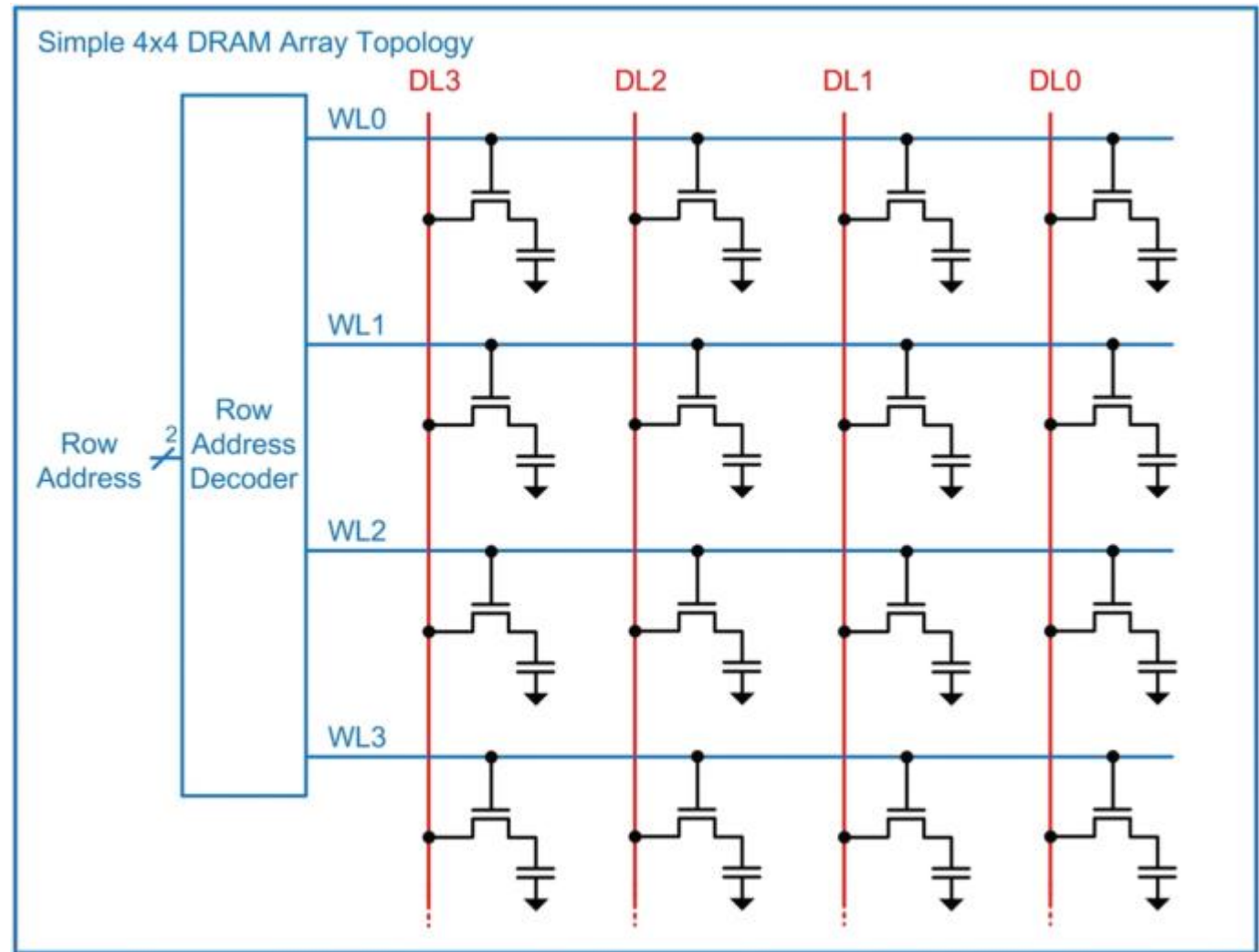
- After **the transistor is turned off**, the charge remains stored in the capacitor, but not for long.
- The capacitor begins to discharge. charge can be maintained for only tens of milliseconds.
- This is because the transistor continues to conduct a tiny amount of current, measured in **picoamperes**, after it is turned off.
- Cell is required to store data for longer time, its content must be periodically *refreshed* by restoring **capacitor charge to its full value**.

Memory Cell: DRAM

- Information stored in the cell can be retrieved correctly only if it is read before the charge in the capacitor drops below some threshold value.
- A sense amplifier connected to the bit line detects whether the **charge stored in the capacitor is above or below the threshold value**.
- **If the charge is above the threshold:**
 - Sense amplifier drives the bit line to **the full voltage representing the logic value 1**.
 - As a result, the capacitor is recharged to the full charge corresponding to the **logic value 1**.
- **If the charge in the capacitor is below the threshold value:**
 - It pulls the bit line to ground level to discharge the capacitor fully (**logic value 0**).
 - Thus, reading the contents of a cell automatically refreshes its contents.

Since the word line is common to all cells in a row, all cells in a selected row are read and refreshed at the same time.

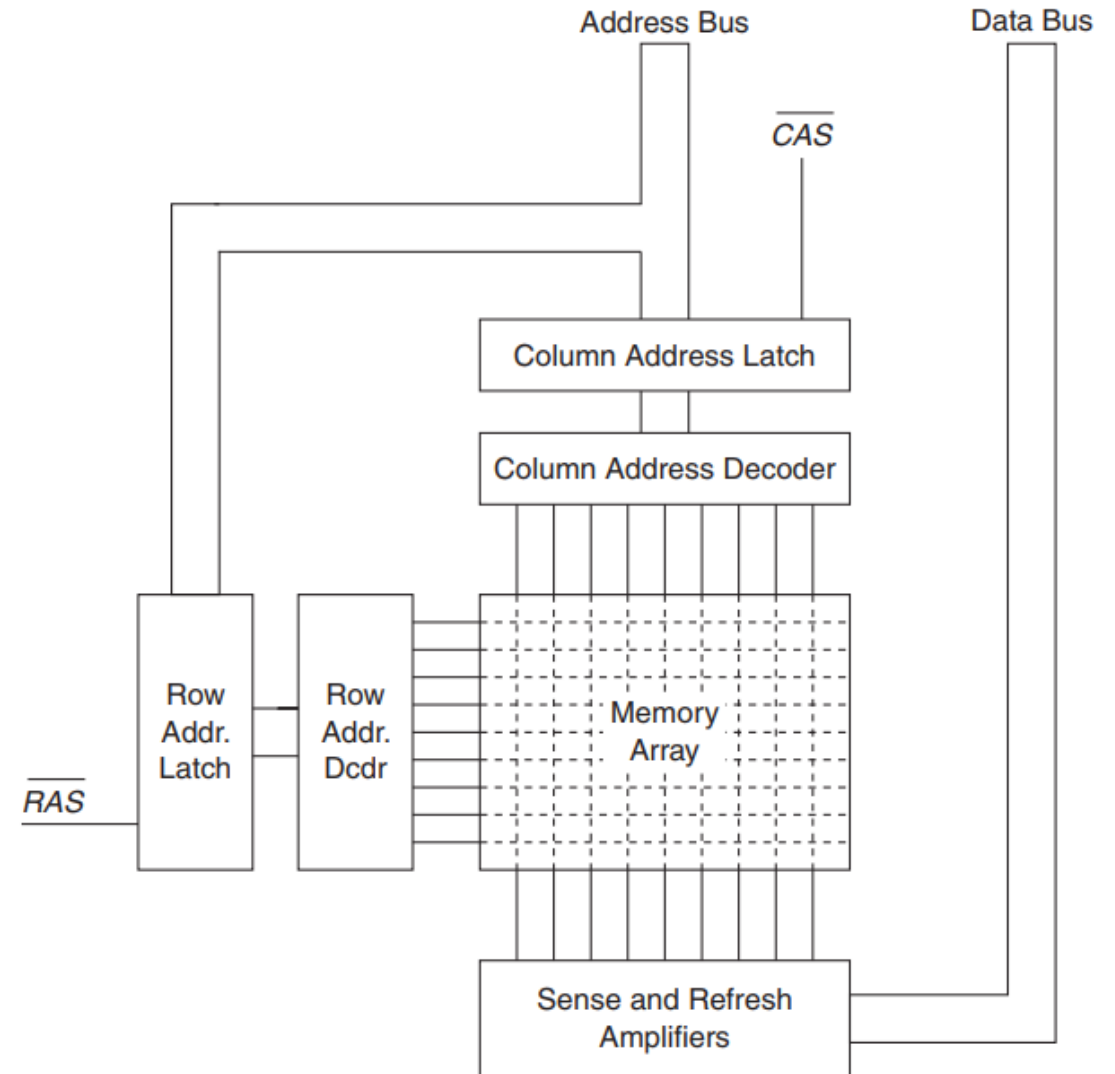
Memory Cell: DRAM



Internal diagram of a DRAM chip

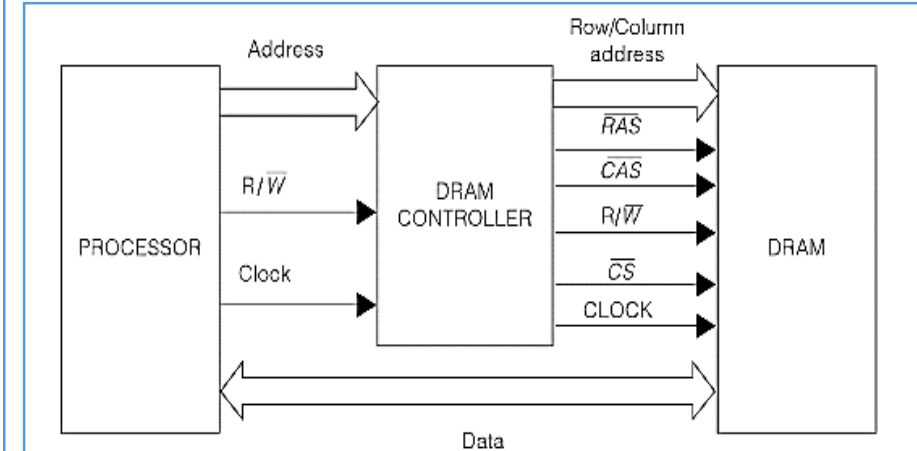
Each cell has a unique location or address defined by intersection of row and a column.

- i) The row address is placed on the rows and given sufficient time to stabilize and be latched.
- ii) The row address strobe \overline{RAS} signal is then activated.
- iii) The row address decoder selects the proper row.
- iv) Next, the column address is placed on the same address lines and allowed to stabilize and be latched.
- v) The column address strobe \overline{CAS} signal is then activated.
- vi) The \overline{CAS} pin also serves as the output enable, so once the \overline{CAS} signal has been stabilized, the sense amps place the data from the selected row and column, on the data bus.
- vii) With this, the data in the selected address is available at the output buffers of the chip, and it is transferred to the data bus.



Memory Control of DRAM

- **Word line** and **bit line** are connected as shown to select the required bit within memory to be read or written to.
- Multitudes of Such cells form word consisting of bits.
- Memory addresses are decoded and converted as rows and columns of matrix that memory elements are arranged in.
- Processor when address memory sends the complete address on its address pins.
- Between **processor** and **DRAM** chip there is a **memory controller** whose function is to split the address into two as columns and rows.
- The **memory controller** should also generate the signals necessary for reading or writing to DRAM.



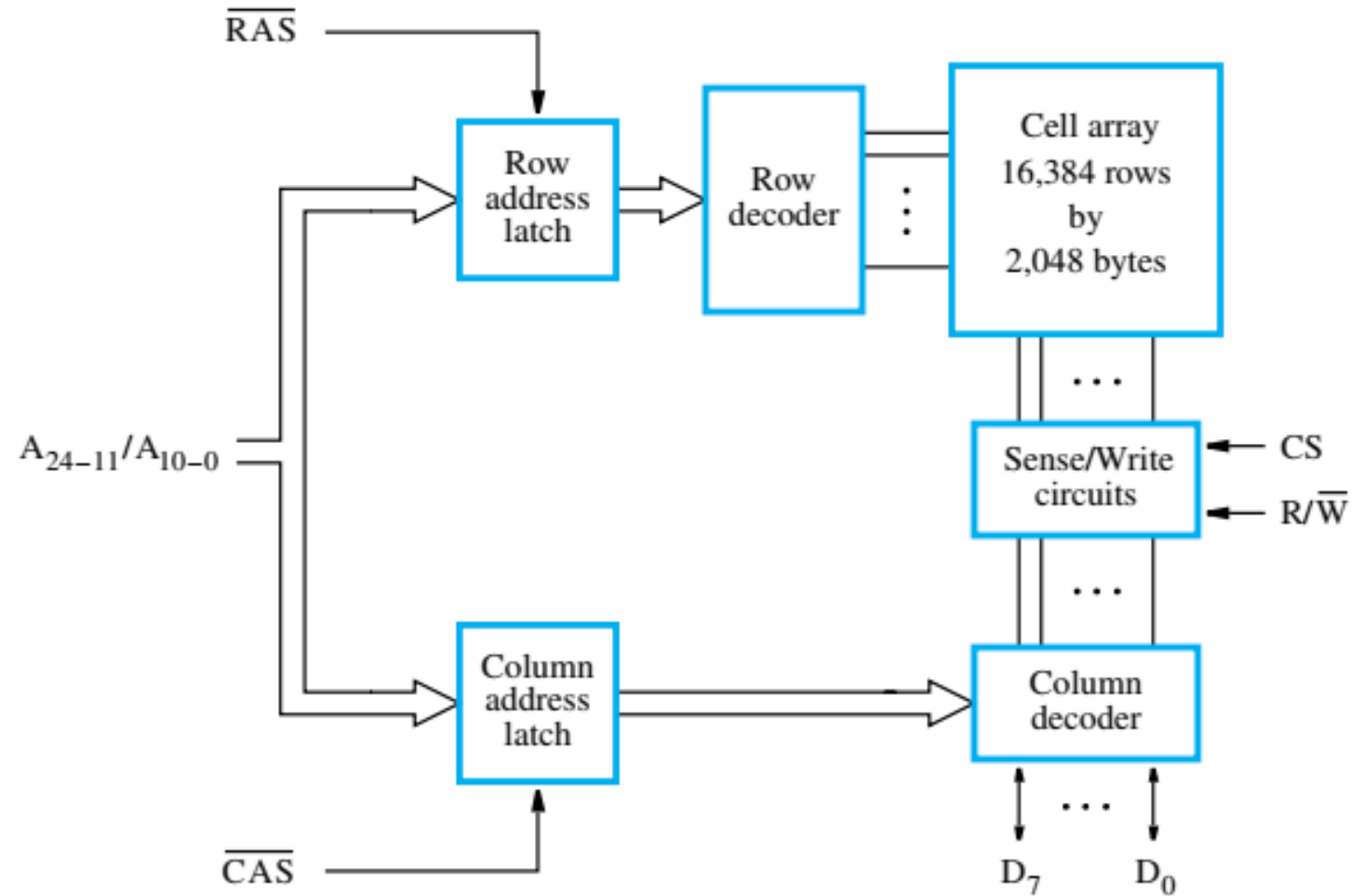
DRAM: 256-Megabit chip

Internal organization of a **32M × 8** DRAM chip.

In commercial DRAM chips, the **RAS** and **CAS** control signals are **active when low**.

RAS: row address strobe

CAS: column address strobe



DRAM: 256-Megabit chip

- **256-Megabit DRAM** chip, configured as **32M×8**, is shown in the above Figure
- The cells are organized in the form of a **16K×16K** array.
- The **16,384** cells in each row are divided into **2,048** groups of 8, forming 2,048 bytes of data.
- Therefore, **14 address bits are needed to select a row**, and another **11 bits are needed to specify a group of 8 bits** in the selected row.
- In **total**, a **25-bit** address is needed to access a byte in this memory.
- The high-order 14 bits and the low-order 11 bits of the address constitute the row and column addresses of a byte, respectively.

DRAM: Refreshing

- The refresh rate of DRAM depends on the temperature and the DRAM standard:
 - DDR5 and LPDDR5: refresh period of **32 milliseconds at 85°C**.
- JEDEC standard:
 - **refresh rate of 64 milliseconds** at normal temperatures (<85°C)
 - **32 milliseconds** at high temperatures (>85°C)

How is refreshing done?

- There are many methods for refresh and one commonly used method is **ROR (RAS only Refresh)**. **By activating each row using RAS.**

DRAM: Refreshing

- **DRAM controller** takes care of scheduling the refreshes and making sure that they do not interfere with regular reads and writes.
- So to keep the data in DRAM chip from leaking away, the **DRAM controller periodically sweeps through all of the rows by cycling repeatedly** and placing a series of row addresses on the address bus.
- This method is designated as **ROR** or **RAS Only Refresh**.
- To **reduce the number of refresh cycles**, one method of design is to split the address such that there are fewer rows and more columns.
- So, the DRAM array is then a **rectangular array**, rather than a **square one**.

Synchronous DRAM

- In **Asynchronous DRAM**, access timing is **not related to the system clock** at all.
- In **Synchronous DRAM**, access are **synchronized with system clock** and SDRAM is currently the RAM that is used as primary memory in general purpose computer systems.
- **Synchronization with system clock easier control of the memory access operations.**
- **SDRAMs have built-in refresh circuitry**, with a refresh counter to provide the addresses of the rows to be selected for refreshing.
- As a result, the dynamic nature of these memory chips is almost invisible to the user.

Synchronous Vs Asynchronous DRAM

Asynchronous

- Does **not share any common clock with CPU**, the controller chips have to manipulate the DRAM's control pins based on all sorts of timing considerations.
- For Accessing Memory, toggling of the external control inputs has a direct effect on internal memory array.

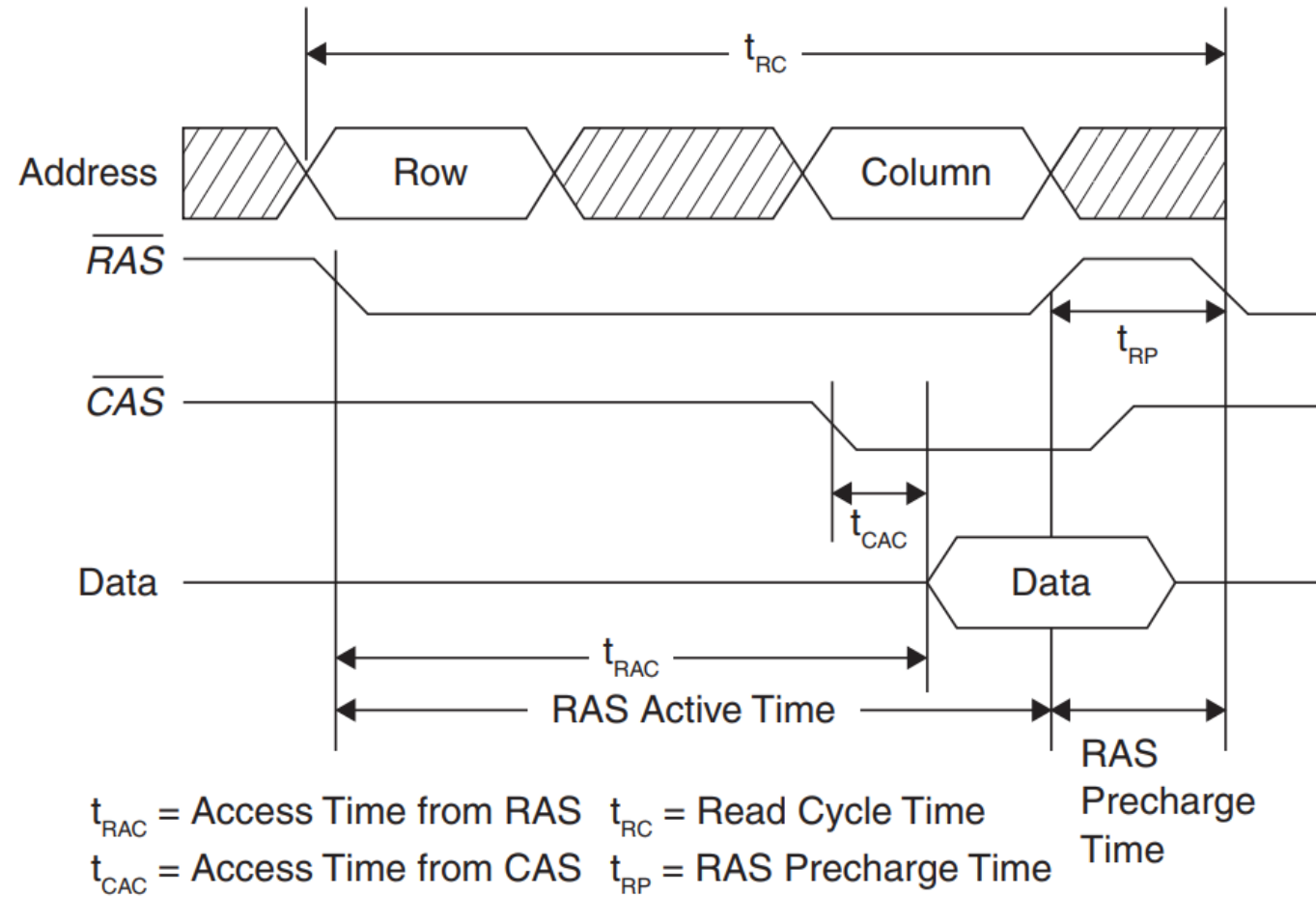
synchronous

- Shares a common clock with CPU, commands can be placed on its control pins on clock edges.
- In SDRAM, the input signals are latched into control logic block which functions as input to a state machine.
- State Machine controls memory Access.
- Read, write and refresh are initiated by loading control commands into device.

DDR (Double Data Rate) SDRAM

- It can be made to transfer data at rising and falling edges of the clock, instead of just at rising edge.
- The key idea is to take advantage of the fact that a **large number of bits are accessed at the same time** inside the chip when a row address is applied.
- To make the best use of the available clock speed, **data are transferred** externally on both the **rising** and **falling edges** of the clock.
- That is why it is called **double the data rate**.
- **Several versions of DDR chips have been developed:**
 - **DDR, DDR2, DDR3, and DDR4** with enhanced capabilities in terms of **increased storage capacity, lower power, and faster clock speeds**.

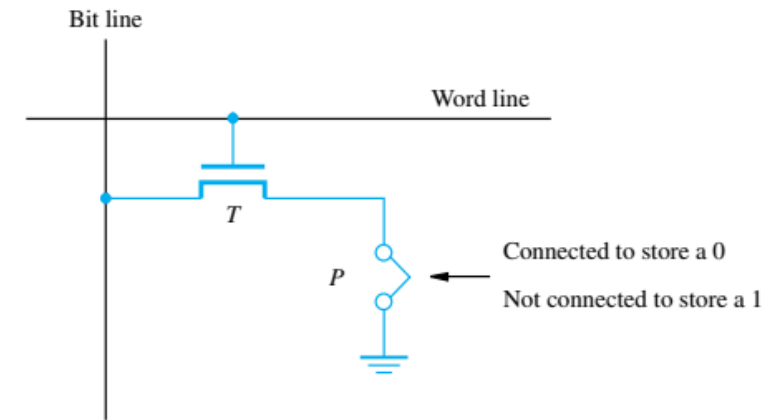
DDR (Double Data Rate) SDRAM



Read-Only Memories

Read-Only Memories

- Both **SRAM** and **DRAM** chips are **volatile**, which means that they retain information only while power is turned on.
- There are many applications requiring memory devices that retain the stored information when power is turned off.

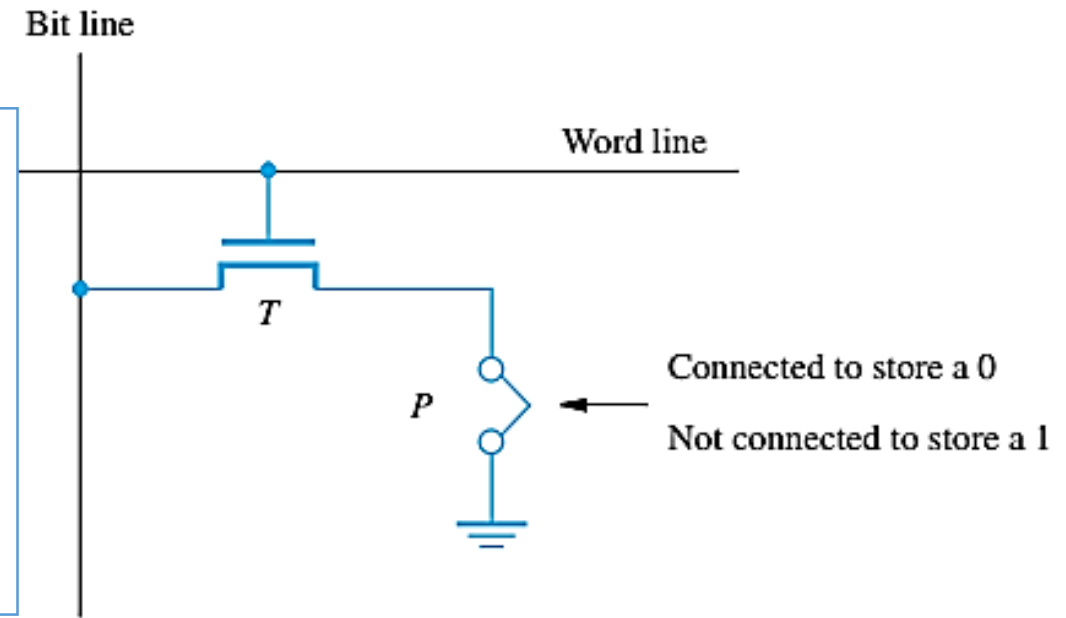


For Example:

- Booting information of a computer.
 - Many embedded systems do not use a hard disk and require nonvolatile memories to store their software. Such as; fire alarm, washing machine etc.
-
- Different types of **nonvolatile** memories have been developed.
 - Generally, their **contents can be read in the same way** and a **special writing process** is needed to place the information into a nonvolatile memory.
 - Since its normal operation involves only reading the stored data, a memory of this type is called a ***read-only memory (ROM)***.

ROM

- A **logic value 0** is stored in the cell if the transistor is connected to ground at point *P*; **otherwise, a 1** is stored.
- The bit line is connected through a resistor to the power supply.
- **To read the state of the cell, the word line is activated to close the transistor switch.**



- As a result, the **voltage on the bit line drops to near zero** if there is a connection between the transistor and ground.
- If there is **no connection to ground**, the **bit line remains at the high** voltage level, indicating a **1**.
- A **sense circuit** at the end of the bit line generates the proper output value.
- The **state of the connection to ground in each cell** is determined when the chip is manufactured, using a mask with a pattern that represents the information to be stored.

PROM

- Some ROM designs allow the data to be loaded by the user, thus providing a *programmable ROM (PROM)*.
- Programmability is achieved by inserting a fuse at **point *P***.
- Before it is programmed, the memory contains all **0s**.
- The user can insert **1s** at the required locations by burning out the fuses at these locations using high-current pulses. (Of course, this process is irreversible).
- PROMs provide flexibility and convenience not available with ROMs.
- The cost of preparing the masks needed for storing a particular information pattern makes **ROMs cost effective only in large volumes**.
- The alternative technology of **PROMs** provides a more convenient and considerably less expensive approach, because memory chips can be programmed directly by the user.
- **Types of PROMS: EPROM and EEPROM**

PROM: EPROM and EEPROM

EPROM (Erasable and Programmable ROM):

- Contents can be erased by exposing to **ultraviolet radiation**.
- Such ROMs have a window through which UV light is applied in the chip.

EEPROM (Electrically Erasable PROM):

- Erasure can be done while chip is on circuit board.
- Programmer can change the data one byte at a time, takes long time when erasing.
- EEPROM is non-volatile, but also erasable and reprogrammable
- Used for data storage in small quantities where data have to be read frequently, may not have to be changed normally.

Interleaved Memories